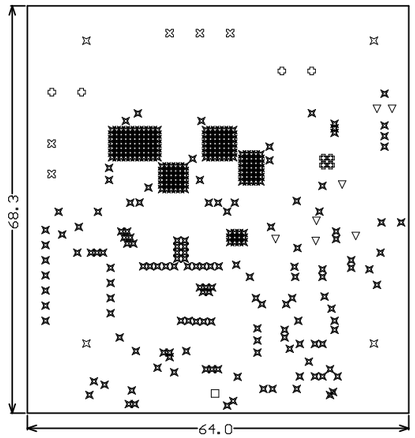
Layer	Name	Material	Thickness	Constant	Board Layer Stack	Board Layer Stack
1	Top Overlay					
2	Top Solder	Solder Resist	0.40mil	3.5		
3	Top Layer	Copper	2.80mil			
4	Dielectric	FR-4	12.00mil	4.2		
5	Mid Layer	Copper	2.80mil			
6	Dielectric	FR-4	34.00mil	4.2		
7	GND Layer	Copper	2.80mil			
8	Dielectric	FR-4	12.00mil	4.2		
9	Bottom Layer	Copper	2.80mil			
10	Solder Side	Solder Resist	0.40mil	3.5		
11	Bottom Overlay					

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✖	355	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
✪	4	12.99mil (0.330mm)	PTH	Round	Top Layer - Bottom Layer	
▽	7	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
✪	4	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	1	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	5	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⌑	4	140.00mil (3.556mm)	PTH	Round	Top Layer - Bottom Layer	
	380 Total					



DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

1000.00mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00365	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Mechanical99	TID #: TIDA-00365		
PLOT NAME = Fabrication Drawing	GENERATED : 5/3/2016 4:25:41 PM		TEXAS INSTRUMENTS

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TEXAS INSTRUMENTS

PROJECT TITLE: Full_Bridge_Power_Stage
DESIGNED FOR: Public Release
FILE NAME: TIDA00365.PcbDoc

ENGINEER:	LAYOUT BY:
V.Pizzolante	V.Pizzolante
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.9.368